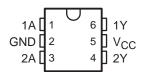
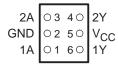
- **Available in the Texas Instruments** NanoStar™ and NanoFree™ Packages
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max tpd of 5.4 ns at 3.3 V
- Low Power Consumption, 10-µA Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- Typical V_{OI P} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at V_{CC} = 3.3 V, T_A = 25°C
- **Ioff Supports Partial-Power-Down Mode** Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 1000-V Charged-Device Model (C101)

DBV OR DCK PACKAGE (TOP VIEW)



YEA, YEP, YZA, OR YZP PACKAGE (BOTTOM VIEW)



description/ordering information

This dual Schmitt-trigger buffer is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC2G17 contains two buffers and performs the Boolean function Y = A. The device functions as two independent buffers, but because of Schmitt action, it may have different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

ORDERING INFORMATION

TA	PACKAGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING‡		
−40°C to 85°C	NanoStar™ – WCSP (DSBGA) 0.17-mm Small Bump – YEA		SN74LVC2G17YEAR		
	NanoFree™ – WCSP (DSBGA) 0.17-mm Small Bump – YZA (Pb-free)	Reel of 3000	SN74LVC2G17YZAR	0.7	
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP		SN74LVC2G17YEPR	C7_	
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)		SN74LVC2G17YZPR		
	007 (007 00) DD) (Reel of 3000	SN74LVC2G17DBVR	047	
	SOT (SOT-23) – DBV	Reel of 250	SN74LVC2G17DBVT	C17_	
	SOT (SC-70) – DCK	Reel of 3000	SN74LVC2G17DCKR	C7	
	301 (30-70) - DCK	Reel of 250	SN74LVC2G17DCKT	01_	

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at

DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site. YEA/YZA, YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition $(1 = SnPb, \bullet = Pb-free).$



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NanoStar and NanoFree are trademarks of Texas Instruments

description/ordering information (continued)

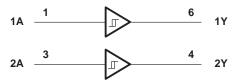
NanoStar[™] and NanoFree[™] package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
Н	Н
L	L

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} –0.5 V to 6.5 V
Input voltage range, V _I (see Note 1)
Voltage range applied to any output in the high-impedance or power-off state, VO
(see Note 1)
Voltage range applied to any output in the high or low state, V _O
(see Notes 1 and 2)
Input clamp current, I_{IK} ($V_I < 0$)
Output clamp current, I _{OK} (V _O < 0)
Continuous output current, IO ±50 mA
Continuous current through V _{CC} or GND±100 mA
Package thermal impedance, θ _{JA} (see Note 3): DBV package
DCK package
YEA/YZA package 143°C/W
YEP/YZP package 123°C/W
Storage temperature range, T _{stq} 65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. The value of V_{CC} is provided in the recommended operating conditions table.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
Vcc	Supply voltage	Operating	1.65	5.5	V	
VI	Input voltage	•	0	5.5	V	
VO	Output voltage		0	Vcc	V	
		V _{CC} = 1.65 V		-4		
		V _{CC} = 2.3 V		-8		
IOH	High-level output current			0 V _{CC}	mA	
		VCC = 3 V	0 5.5 0 V _{CC} -4 -8 -16 -24 -32 4 8 16			
		V _{CC} = 4.5 V				
		V _{CC} = 1.65 V		4		
		V _{CC} = 2.3 V	-4 -8 -16 -24 -32 4 8 16 24 32			
lOL	Low-level output current		Vcc = 3 V		mA	
		ACC = 3 A				
		V _{CC} = 4.5 V		32		
TA	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	v _{cc}	MIN	TYP [†] MAX	UNIT	
		1.65 V	0.7	1.4		
V _{T+}		2.3 V	1	1.7		
Positive-going input		3 V	1.3	2.2	V	
threshold voltage		4.5 V	1.9	3.1		
		5.5 V	2.2	3.7		
		1.65 V	0.3	0.7		
V _T _		2.3 V	0.4	1		
Negative-going input		3 V	0.6	1.3	V	
threshold voltage		4.5 V	1.1	2		
		5.5 V	1.4	2.5		
		1.65 V	0.3	0.8		
ΔVΤ		2.3 V	0.4	0.9		
Hysteresis		3 V	0.4	1.1	V	
$(V_{T+} - V_{T-})$		4.5 V	4.5 V 0.6]	
		5.5 V	0.7	1.4		
	$I_{OH} = -100 \mu\text{A}$	1.65 V to 5.5 V	V _{CC} -0.1			
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			
V	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9		V	
VOH	$I_{OH} = -16 \text{ mA}$	2.1/	2.4			
	$I_{OH} = -24 \text{ mA}$	3 V	2.3			
	$I_{OH} = -32 \text{ mA}$	4.5 V	3.8			
	$I_{OL} = 100 \mu\text{A}$	1.65 V to 5.5 V		0.1		
	I _{OL} = 4 mA	1.65 V		0.45		
M = .	I _{OL} = 8 mA	2.3 V		0.3	V	
V _{OL}	I _{OL} = 16 mA	3 V		0.4	V	
	$I_{OL} = 24 \text{ mA}$	3 V		0.55		
	I _{OL} = 32 mA	4.5 V		0.55		
I _I A input	V _I = 5.5 V or GND	0 to 5.5 V		±5	μΑ	
loff	V_I or $V_O = 5.5 V$	0		±10	μΑ	
Icc	$V_I = 5.5 \text{ V or GND}, \qquad I_O = 0$	1.65 V to 5.5 V		10	μΑ	
ΔlCC	One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	3 V to 5.5 V		500	μΑ	
C _i	$V_I = V_{CC}$ or GND	3.3 V		4	pF	

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	V _{CC} = 1.8 V ± 0.15 V				V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V		UNIT
(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
^t pd	А	Υ	3.9	9.3	1.9	5.7	2.2	5.4	1.5	4.3	ns



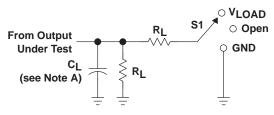
SN74LVC2G17 DUAL SCHMITT-TRIGGER BUFFER

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operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		ER TEST CONDITIONS		V _{CC} = 2.5 V	V _{CC} = 3.3 V	V _{CC} = 5 V	LINUT	
	PARAMETER	TEST CONDITIONS	TYP TYP		TYP	TYP	UNIT	
C _{pd}	Power dissipation capacitance	f = 10 MHz	17	18	19	21	pF	

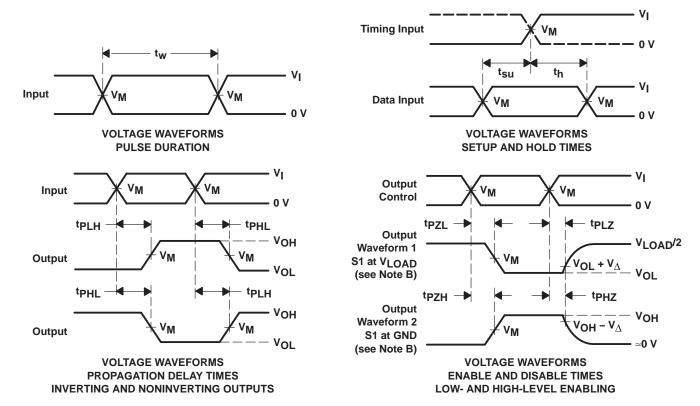
PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
^t PHZ ^{/t} PZH	GND

LOAD CIRCUIT

.,	INF	PUTS	.,	.,		_	.,
VCC	٧ _I	t _r /t _f	VM	VLOAD	CL	RL	V_Δ
1.8 V \pm 0.15 V	VCC	≤ 2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤ 2 ns	V _{CC} /2	2×VCC	30 pF	500 Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V \pm 0.5 V	VCC	≤2.5 ns	V _{CC} /2	2×V _{CC}	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

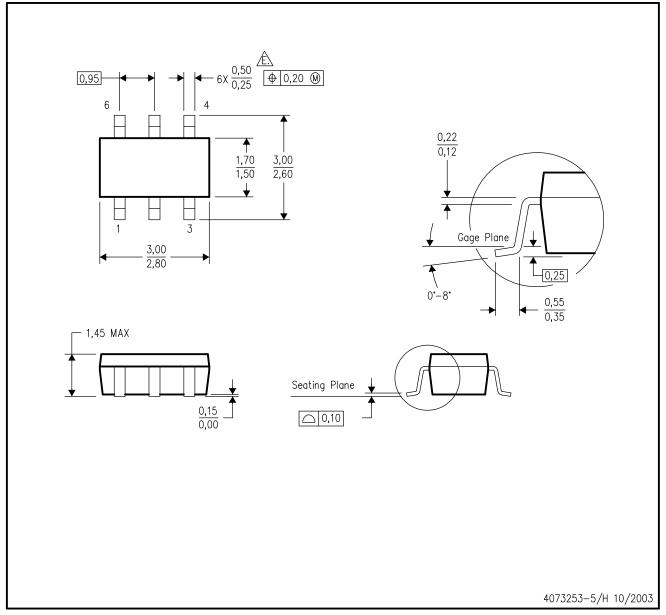
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



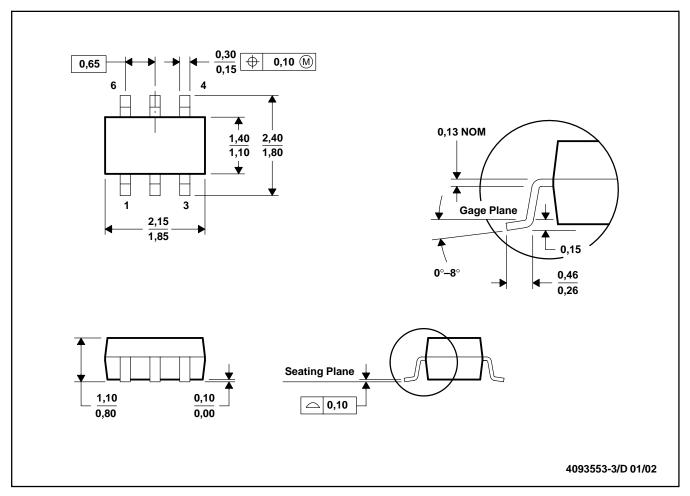
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- Falls within JEDEC MO-178 Variation AB, except minimum lead width.



DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE

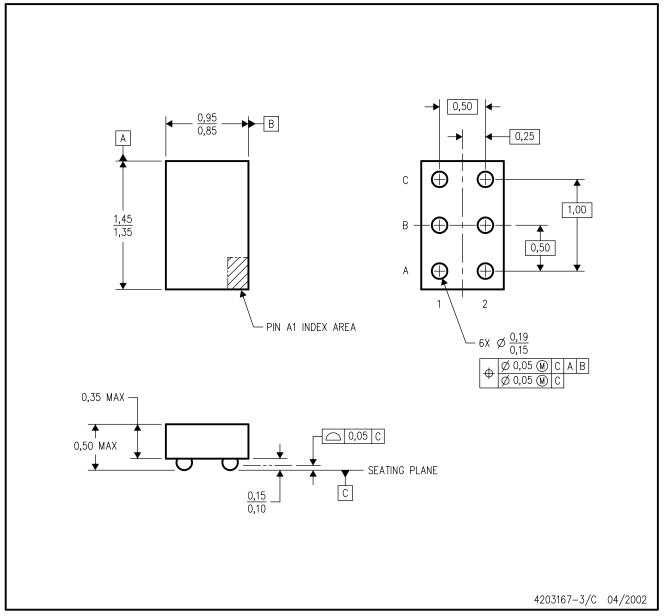


NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-203

YEA (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

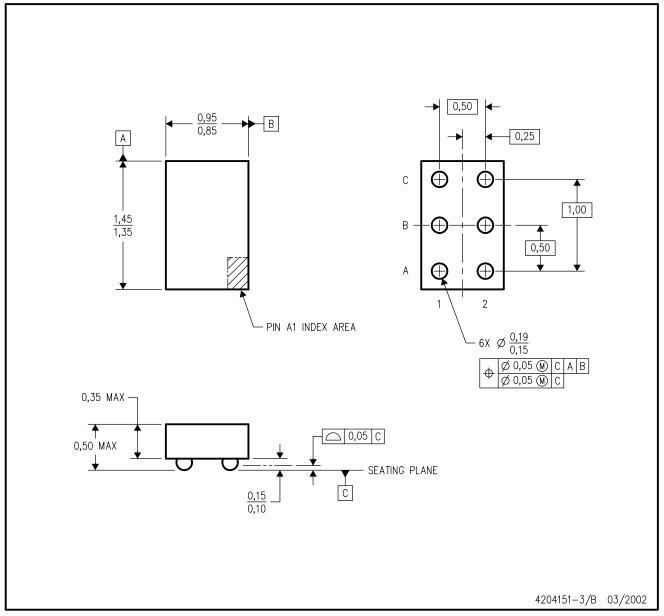
- B. This drawing is subject to change without notice.
- C. NanoStar \mathbf{M} package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is tin-lead (SnPb). Refer to the 6 YZA package (drawing 4204151) for lead-free.

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YZA (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

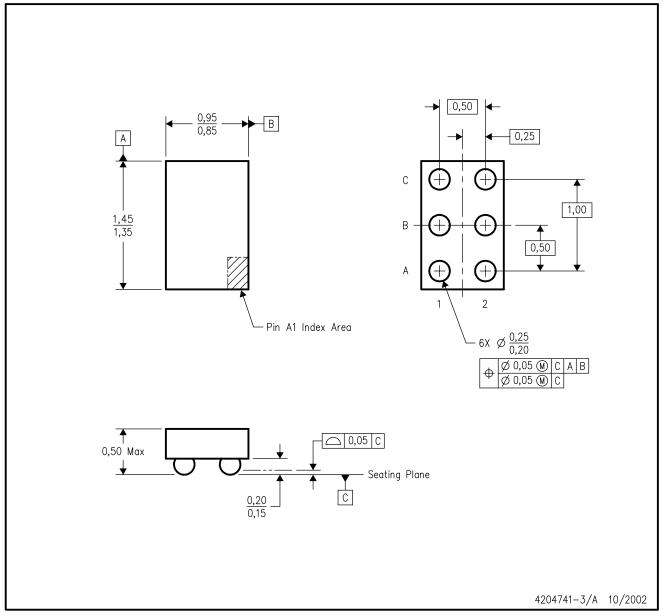
- B. This drawing is subject to change without notice.
- C. NanoFree $^{\text{TM}}$ package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is lead-free. Refer to the 6 YEA package (drawing 4203167) for tin-lead (SnPb).

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YZP (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

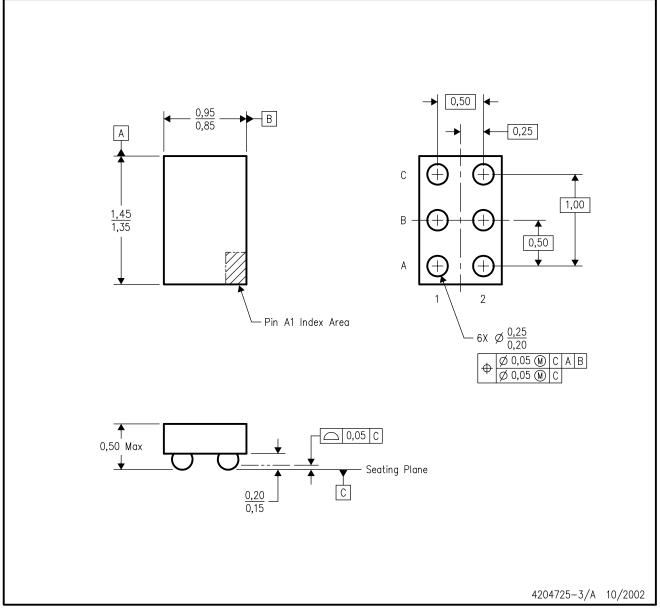
- B. This drawing is subject to change without notice.
- C. NanoFree™ package configuration.
- D. This package is lead-free. Refer to the 6 YEP package (drawing 4204725) for tin-lead (SnPb).

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YEP (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. NanoStar \mathbf{M} package configuration.
- D. This package is tin-lead (SnPb). Refer to the 6 YZP package (drawing 4204741) for lead-free.

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